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The Electromagnetic Engineering Technology as major is one of the programs that offer an opportunity for interdisciplinary education across all the universities. The course mainly implements computers and electronics in engineering systems. The major provides an individual with the opportunity to study coursework in manufacturing, electrical, electronic and mechanical areas with appropriate perquisite courses. As observed, It one of the valid tools in preparing the client to work in controls, technical sales, instrumentation and other areas requiring inter-disciplinary preparation. The course is geared in delivering individuals with relevant expertise in the filling mechanical and electrical vacancies within the economy. These positive aspects have made the course to be one of the most prestigious courses to be offered in various universities across the globe. Today, these are numerous developments that have emerged in the field. These developments indicate how a new state of mind is required in the field of electromechanical. This paper will spell one of the most critical current developments in automotive and mechanical engineering (France 26).

## Molded interconnect devices reshape electromechanical design.

Erick in his work offers incisive and descriptive explanation on how one of the electromechanical engineering technologies has helped reshape the electrical design. In his well written paper, the author provides an enormous view on how the Molded Interconnect Devices (MIDs) have revolutionized the traditional mechanical and electrical designs in application especially in the telecommunication and automotive industries (Yee). However, he is quite remorseful that majority of the engineers still lack the relevant knowledge on the availability and use of these versatile and efficient devices. He believes that Molded Interconnect Devices, are the best options in providing the electromechanically engineers with the best design approaches based on the traditional PC boards (Yee).   
The renowned electrical engineer uses vivid description on how the devise operates and provides various examples of its application levels. In the article, the writer believes that MIDs are the best appliances in replacing several components of the circuit-board product. This preference is made due to their ability to integrate both the mechanical and electrical function into a single piece. In turn, these products make an important contribution in the entire design in terms of manufacturing and assembly of the whole system. He further reminds the engineers on how the product is cost effective and relevant to use in the field. He believes that, unlike the Pc boards which are simply limited to two dimensional applications, the MIDs are capable of providing the 3D circulatory (Yee).   
In a forceful yet articulate voice, Rick further reminds the audience that MIDs are quite vital in the various areas of automotive application. The automotive applications are one of the wide and important areas of the electromechanical technologies. In the application, the MID technology is capable of providing brake light fixture. Unlike the traditional fixtures which included a stamped metal insert, a connector and soled-attached wiring in molded housing, the MID version combines the connector and the housing into a single piece. The author believes that, through the selective plating, this devise is capable of incorporating the required circulatory to be used in the electromechanical engineering. The second era is the application on the antenna where they are used as antennae stub or retractor. This application enables the volume limitation in the cell phones thus providing efficiency and space (Yee).   
In computer application, the MIDs have been quite useful in providing solutions to devices like joysticks. The devise offers a three dimension approach in providing the pull and push button. The same application is quite important in the consumer and industrial products. Many products such as lamps and flashlights have used the application to make materials such as brake lights. Further, the manufacturers may utilize the injection-molding capacity of the technology to integrate their electrical components within the ergonomically and aesthetically pleasing figures. Further the electromechanical engineers may use the opportunity of high temperatures within the system to accommodate the heated industrial conditions and soldering processes. As a result, the outdated industrial assemblies that were once nuisances may be renovated through fabrication to make them relevant (Yee).   
In his paper France, the experienced engineer uses the opportunity to describe the critical overview on how the machine operates. He provides a detailed description of the operation. He further uses the various forms of bonding in order to integrate the process. He believes that, better bonding is possible through use of mechanical interlocks on the devise so as the first and the second short are in cooperated. In addition, he provides the electromechanical engineer with the various parameters that needs to be included while developing the devise. He advises the engineers to select proper materials with prompt thermoplastics and low cost performance. These properties will enable the application of the machine to be efficient and effective.   
In conclusion, the article is a great source for engineers aiming to achieve and implement on the electrical and automotive lines. The paper provides a great electromechanical guidelines and process capabilities within extend and positive range (France 26). It provides the relevant knowledge that is necessary not only to learners but also to the automatic and telecommunication industries.

## Works Cited

France, Sarah. " Examining the Future of Electromechanical Service." Electrical Apparatus 52. 6 (1999): 26   
Yee, Eric. " Molded Interconnect Devices Reshape Electromechanical Design." Electronic Design 48. 18 (2000): 141.